## COMBINED DECLARATION AND POWER OF ATTORNEY CONTINUED

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patents issued thereon.

Signature: Tax, Su		Date:	Jun 23	2003
Sole or First Joint Inventor: Tao, Su		_		
Citizenship: Taiwan, R.O.C.				
Residence and Post Office Address: No R	o. 72-2, <b>T</b> sungshih R.O.C.	ı Hsin-tsun,	, Tsoying Chu, K	(aohsiung, Taiwan,
Signature:	in Lo.	Date:	Jun >3	>003
Second Joint Inventor (if any): Kuang-Li	in Lo			
Citizenship: Taiwan, R.O.C.				
Residence and Post Office Address: Ka	No. 50, Shen-N aoshiung Hsien,			, Ta-Shu Shiang,
Signature: Sung Sheng L	see	Date:	Tun 23	2003
Third Joint Inventor (if any): Tsung-Sher	ng Lee			
Citizenship: Taiwan, R.O.C.				
Residence and Post Office Address: No	o. 23, Liao-Ning I	St., Kaoshi	iung, Taiwan, R.	.O.C.
Signature: Yaw Yuh	Tang.	Date:	Jun	~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~ ~
Fourth Joint Inventor (if any): Yaw-Yuh				
Citizenship: Taiwan, R.O.C.				
Residence and Post Office Address: 5F,	f, No. 7, Alley 21, aiwan, R.O.C.	Lane 399,	Sec. 3, Chungh	nua E Rd., Tainan,
Signature: <u>Van - Kai</u>	Tao	Date:	Jun 23	200}
Fifth Joint Inventor (if any): Yuan-Kai Ta				
Citizenship: Taiwan, R.O.C.				

Residence and Post Office Address: No. 1-1, Lane 98, Hua-Shang Rd., Chu-Hu Tsuen, Lu-Chu

Shiang, Kaohsiung Hsien, Tawian, R.O.C.

## COMBINED DECLARATION AND POWER OF ATTORNEY

As the below named inventor, I hereby declare that:

FAX: 886-2-2369 7233

My residence, post office address and citizenship are as stated below next to my name and that I believe I am an original, first and sole inventor (if only one name is listed below) or an original, first and joint inventor (if plural names are listed below) of the subject matter which is claimed and for which a patent is sought on the invention entitled

## CHIP PACKAGE STRUCTURE AND METHOD FOR MANUFACTURING THE SAME

the specification of wh	nich						
_X is attached here was filed on	to.						
as Application S	as Application Serial No and was amended on						
specification, including I acknowledge to application in accorda I hereby claim for application(s) for pat	g the claims, as amende he duty to disclose info nce with Title 37, Code o reign priority benefits un ent or inventor's certific patent or inventor's cert timed:	and understand the content of by any amendment referred ormation which is material to of Federal Regulations, § 1, ander Title 35, United States Co cate listed below and have dificate having a filing date be	ed to above. o the patent o.56(a). Code, § 119 also identifi	ability of this of any foreign ied below any			
Number	Country	Date Filed(yyyy/mm/dd)	Yes	No			
91137974	Taiwan, R.O.C.	2002/12/31	Х				
= ::	=	30)		lication and to			
SEND CORRESPONDENCE TO:			DIRECT TELEPHONE CALLS TO: (Name and telephone number)				
			da Lee				